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Contents

OPENING SESSION: DAY ONE

11908 02	Photomask challenges for data-centric computing in the 2020s (Keynote Paper) [11908-34]
11908 03	Advanced AFM nanomachining: high aspect repairs [11908-23]
	ML & MPC
11908 04	Model-based mask process correction for EUV mask [11908-26]
11908 05	A deep learning toolset to mask analysis with SEM digital twins [11908-27]
11908 06	Model-driven rule-based mask process correction [11908-18]
	EUV FROM ASIA I
11908 07	Fundamental research activities on EUV lithography at NewSUBARU synchrotron light facility (Invited Paper) [11908-16]
	LITHOGRAPHY
11908 08	Stereophonic projection lithography using parabolic mirrors [11908-2]
11908 09	Automatic design of the build-in lens mask for three-dimensional photo lithography [11908-8]
	PSM, ETCHING & FPD
11908 0A	Study of high-transmission PSM for lithographic performance and defect control [11908-25]
11908 OB	Proposal of new style defect quality assurance for flat panel display photomask [11908-9]

OPENING SESSION: DAY TWO

11908 OC	eBeam initiative surveys report upbeat photomask market outlook (Invited Paper) [11908-20]
	NIL
11908 OD	Self-aligned double patterning process for sub-15nm nanoimprint template fabrication [11908-31]
11908 OE	NIL integration using computational lithography for semiconductor device manufacturing [11908-15]
11908 OF	Nanoimprint performance improvements for high volume semiconductor device manufacturing [11908-14]
	EUV FROM ASIA II
11908 0G	Investigation of EUV pellicle mechanical stress within EUV pod [11908-6]
	INSPECTION
11908 OH	INSPECTION Actinic patterned mask inspection for EUV lithography (Invited Paper) [11908-28]
11908 OH 11908 OI	INSPECTION Actinic patterned mask inspection for EUV lithography (Invited Paper) [11908-28] High-brightness LDP source for EUVL mask inspection [11908-29]
11908 OH 11908 OI 11908 OJ	INSPECTION Actinic patterned mask inspection for EUV lithography (Invited Paper) [11908-28] High-brightness LDP source for EUVL mask inspection [11908-29] Study of high throughput EUV mask pattern inspection technologies using multi e-Beam optics [11908-10]
11908 OH 11908 OI 11908 OJ 11908 OK	INSPECTION Actinic patterned mask inspection for EUV lithography (Invited Paper) [11908-28] High-brightness LDP source for EUVL mask inspection [11908-29] Study of high throughput EUV mask pattern inspection technologies using multi e-Beam optics [11908-10] The study of a phase difference defect inspection technology [11908-1]
11908 OH 11908 OI 11908 OJ 11908 OK	INSPECTION Actinic patterned mask inspection for EUV lithography (Invited Paper) [11908-28] High-brightness LDP source for EUVL mask inspection [11908-29] Study of high throughput EUV mask pattern inspection technologies using multi e-Beam optics [11908-10] The study of a phase difference defect inspection technology [11908-1]
11908 OH 11908 OI 11908 OJ 11908 OK	INSPECTION Actinic patterned mask inspection for EUV lithography (Invited Paper) [11908-28] High-brightness LDP source for EUVL mask inspection [11908-29] Study of high throughput EUV mask pattern inspection technologies using multi e-Beam optics [11908-10] The study of a phase difference defect inspection technology [11908-1] WRITING & CD ANALYSIS
11908 OH 11908 OI 11908 OJ 11908 OK 11908 OL	INSPECTION Actinic patterned mask inspection for EUV lithography (Invited Paper) [11908-28] High-brightness LDP source for EUVL mask inspection [11908-29] Study of high throughput EUV mask pattern inspection technologies using multi e-Beam optics [11908-10] The study of a phase difference defect inspection technology [11908-1] WRITING & CD ANALYSIS Multi-beam mask writer, MBM-2000 [11908-33]
11908 OH 11908 OI 11908 OJ 11908 OK 11908 OL 11908 OM	INSPECTION Actinic patterned mask inspection for EUV lithography (Invited Paper) [11908-28] High-brightness LDP source for EUVL mask inspection [11908-29] Study of high throughput EUV mask pattern inspection technologies using multi e-Beam optics [11908-10] The study of a phase difference defect inspection technology [11908-1] WRITING & CD ANALYSIS Multi-beam mask writer, MBM-2000 [11908-33] Novel method to find the best process point in e-beam mask making [11908-32]

	POSTER SESSION
11908 00	Ongoing development of ultrafast DUV pulse laser repair for EUV photomasks [11908-24]
11908 OP	Spectra of high energy ions as debris in laser-produced plasma EUV source [11908-21]
11908 OQ	Birefringence mapping of optical material by use of supercontinuum vector beams [11908-22]
11908 OR	Efficient VIA position optimization for yield enhancement [11908-3]
11908 OS	Damage-less removal of surface contamination using atomic hydrogen generated on heated tungsten mesh [11908-4]
11908 OT	Beyond EUV measurement at NewSUBARU synchrotron light facility [11908-17]
11908 OU	Hydrogen damage and cleaning evaluation of Mo/Si multilayer using high-power EUV irradiation tool [11908-19]
11908 0V	The application of reticle analyzer in DRAM fab [11908-5]

OPENING SESSION: DAY TWO: ADDITIONAL PAPER

11908 0WIn-line airborne particle sensing supports faster response to contamination excursions
[11908-36]